

PATENT ABSTRACTS OF JAPAN

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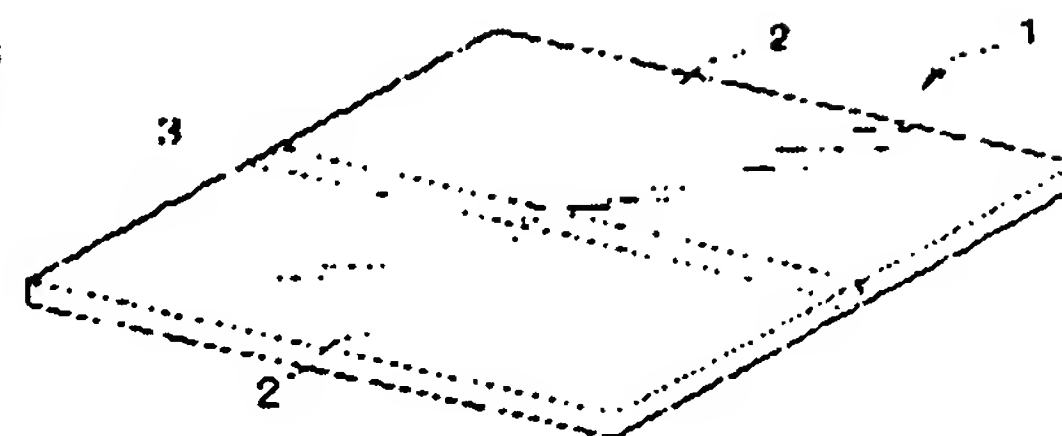
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(54) SPUTTERING TARGET, AND ITS PRODUCTION METHOD

(57)Abstract:

PROBLEM TO BE SOLVED: To provide a large-sized sputtering target which can be produced at a relatively low cost, and in which the intrusion of impurities can be suppressed.

SOLUTION: The sputtering target 1 is formed by arranging a plurality of planar target constituting members 2 in the same plane and subjecting the members to friction stir joining each other. In the method of producing the sputtering target 1, a plurality of planar target constituting members 2 are arranged in the same plane so that the adjoining ones are abutted on each other, a probe of a tool for friction stir joining is implanted in the abutted part of the adjoining target constituting members 2 so as to be laid across the both. Thereafter, the target constituting members 2 and the probe are relatively moved, so that the probe 2 is moved over the whole length of the abutted part, and the target constituting members 2 are mutually subjected to friction stir joining.



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